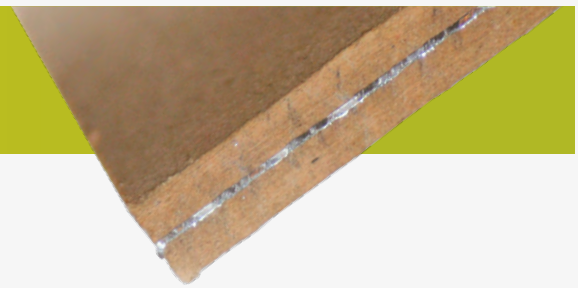
H-Flachs Composite Boards



Aluminium-HDF-Substrate

Range of application

Aluminium-HDF-substrates are being used in the construction of interior doors with climate class requirements as a vapour control layer. The processing company is responsible for testing if our product meets his guidelines of application.

Composition

Surface layer: 2 x Wood Fibre Board corr. DIN EN 622-2 thickness 1,6 to 4,0 mm

Middle layer: 1 x Aluminium sheet AL 99,5, thickness 300µ/500µ

Bonding: PVAc D-3 Glue, on request with Isocyanides cross linker

Handling and Storage

Handling
Aluminium-HDF-substrates shall be used in process only when cooled down approximately 4 days after production. Static electricity is to be avoided.

Storage
The panels shall be stored only horizontally on a pallet. It has to be insured that the aluminium core sandwich panels cannot absorb moisture. This could result in the delamination of the aluminium due to its reflecting effect. Therefore the storage in a dry and ventilated environment is required. ***When Funder Biofibre is being used:*** due to the fact that Funder boards do not contain biocides or other preservatives a fungal attack can occur when the boards are disposed to condensation and insufficient ventilation.

Processing

- Prior to processing the aluminium-HDF-substrates have to be acclimatized according to the climatic environment of the production facility.
- Suitable glues for processing are urea-based glues, D-3, D-4.
- Press temperature must not exceed 90 °C during processing.
- Depending on the used glue the according pressing time is applicable.
- Excessive calibration and/or sanding of the surface layer can result in the delamination of the aluminium core during the processing of the door (steam bubble).

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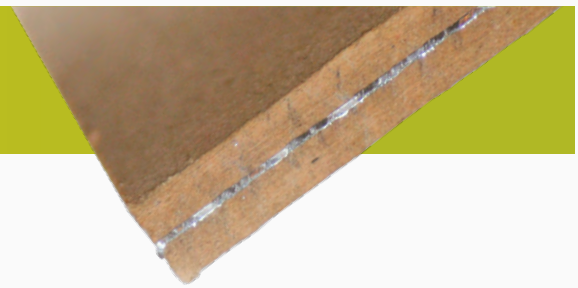

Lead-HDF-Substrate

Range of application

Lead-HDF-substrates are being used in the construction of interior doors with special requirements for radiation shielding and soundproofing. The processing company is responsible for testing if our product meets his guidelines of application.

Composition

Surface layer: 2 x Wood Fibre Board corr. DIN EN 622-2 thickness 1,6 to 4,0 mm

Middle layer: 1 x Sheet of lead, thickness 500µ/1000µ/1500µ/2000µ

Bonding: PVAc D-3 Glue

Handling and Storage

Handling
Lead-HDF-substrates shall be used in process only when cooled down approximately 4 days after production. Static electricity is to be avoided.

Storage
The panels shall be stored only horizontally on a pallet. It has to be insured that the lead core sandwich panels cannot absorb moisture. This could result in the delamination of the lead due to its reflecting effect. Therefore the storage in a dry and ventilated environment is required.
When Funder Biofibre is being used: due to the fact that Funder boards do not contain biocides or other preservatives a fungal attack can occur when the boards are disposed to condensation and insufficient ventilation.

Processing

- Prior to processing the lead-HDF-substrates have to be acclimatized according to the climatic environment of the production facility.
- Suitable glues for processing are urea-based glues, D-3, D-4.
- Press temperature must not exceed 90 °C during processing.
- Depending on the used glue the according pressing time is applicable.
- Excessive calibration and/or sanding of the surface layer can result in the delamination of the lead core during the processing of the door (steam bubble).

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